

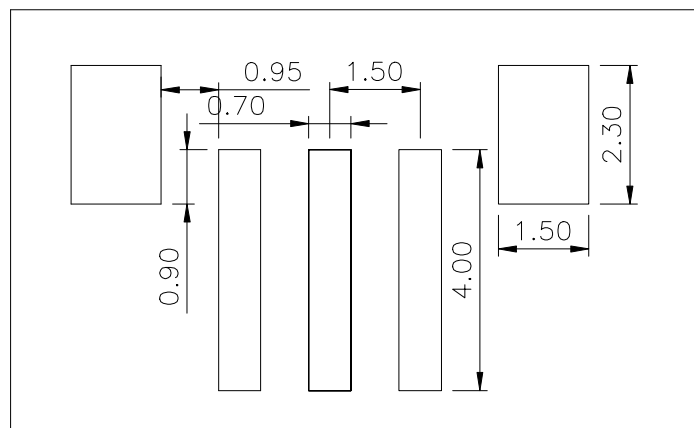
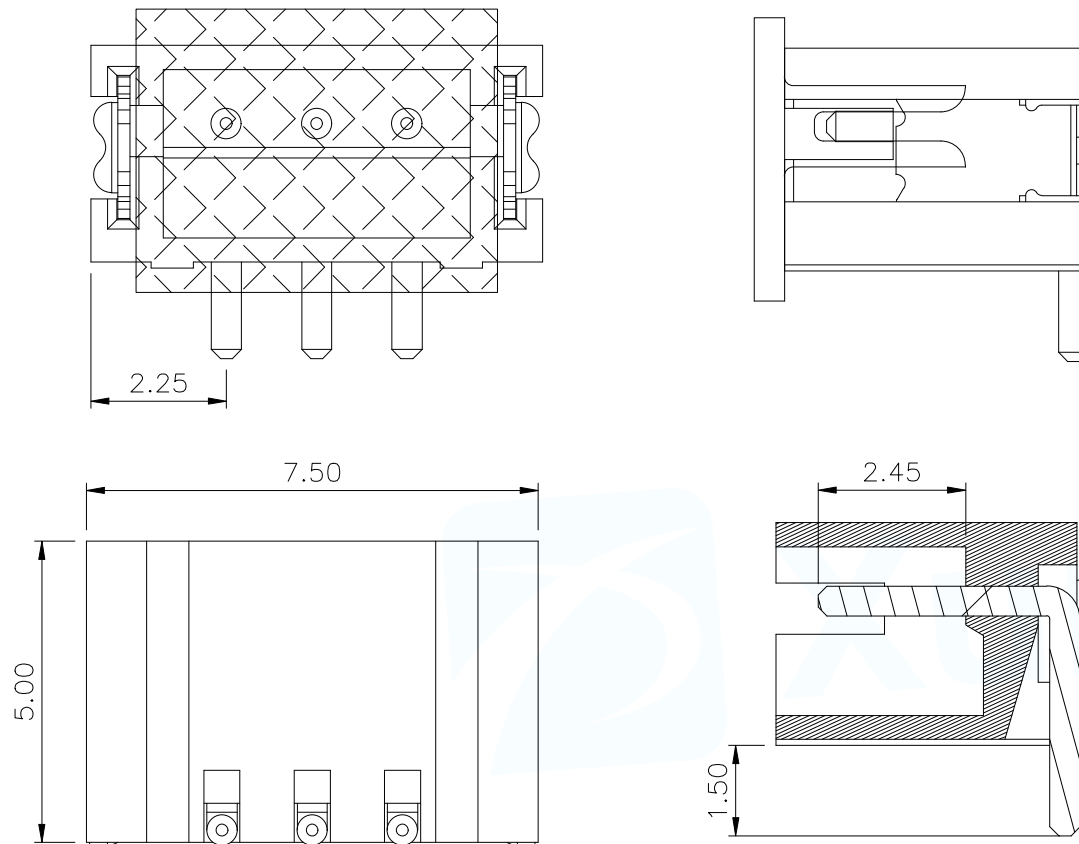
12	13	14	15
MAPX	MODIFICATION	DATE	DRAW APPROVE

NOTES:

- 1.MATERIAL:  
HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V\_0  
CONTACT: COPPER ALLOYS.  
COVER: COPPER ALLOYS OR STEEL.
- 2.PLATING:  
UNDERPLATE: NICKEL.

SPECIFICATIONS:

Voltage Rating:125V AC DC  
Current Rating:1A AC,DC  
Withstanding voltage:500V AC 1/Minute  
Insulation Resistance:100MΩ Min  
Contact Resistance:20mΩ Max  
Temperatuer Range:-25℃ ~+ 85℃



RECOMMENDED P.C.B HOLE LAYOUT

MANUFACTURE DWG			 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: WAFER 1.50 立脚3P	
DECIMALS:	ANGLES:	PAR	WAFER-150L-3P	
X.X:±0.35	X.X':±3°	DWN		
X.XX:±0.25	X.XX:±2'	CHKD		
X.XXX:±0.15		APVD		
CUSTOMER COPY		SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	REV:A